

A1
encl
at least one connection conductor joined to said metal layer
by welding; and

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at least one semiconductor component disposed directly on said
substrate body facing said metal layer.

A2
Claim 4 (amended). The semiconductor module according to
claim 3, wherein said substrate body is at least one of a
direct copper bonded substrate and an active metallic brazed
substrate.

In the Specification:

A3
Replace the paragraph between page ⁵ 4, line 19 and page ⁵ 4, line
21 with the following: -- It is particularly advantageous in
this context for the substrate body to be configured as a DCB
substrate or an active metallic brazed (AMB) substrate.--